



Figure 1: Photograph of inside cover



Figure 2: Photograph of circuit board assembled on base (1)

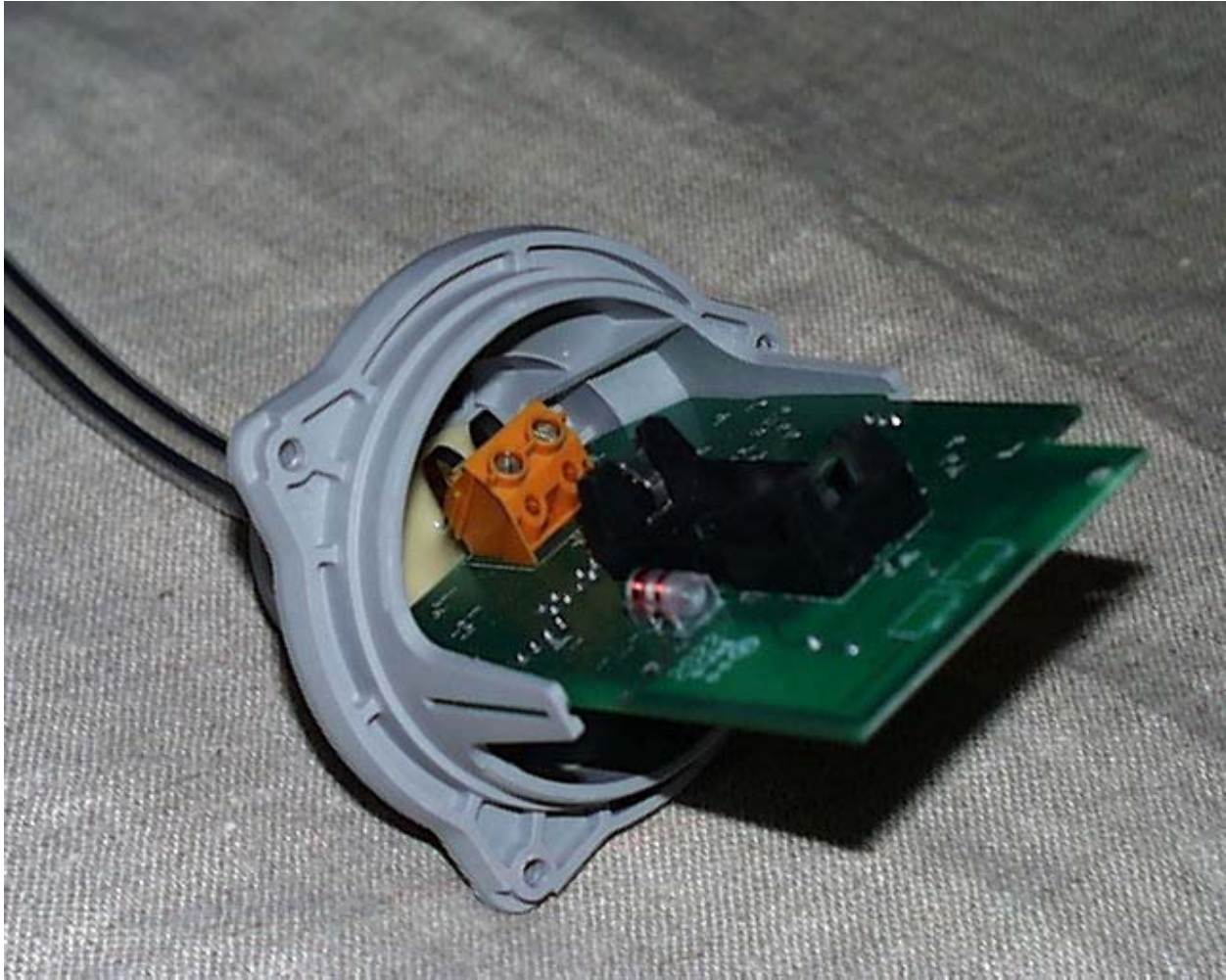


Figure 3: Photograph of circuit board assembled on base (2)

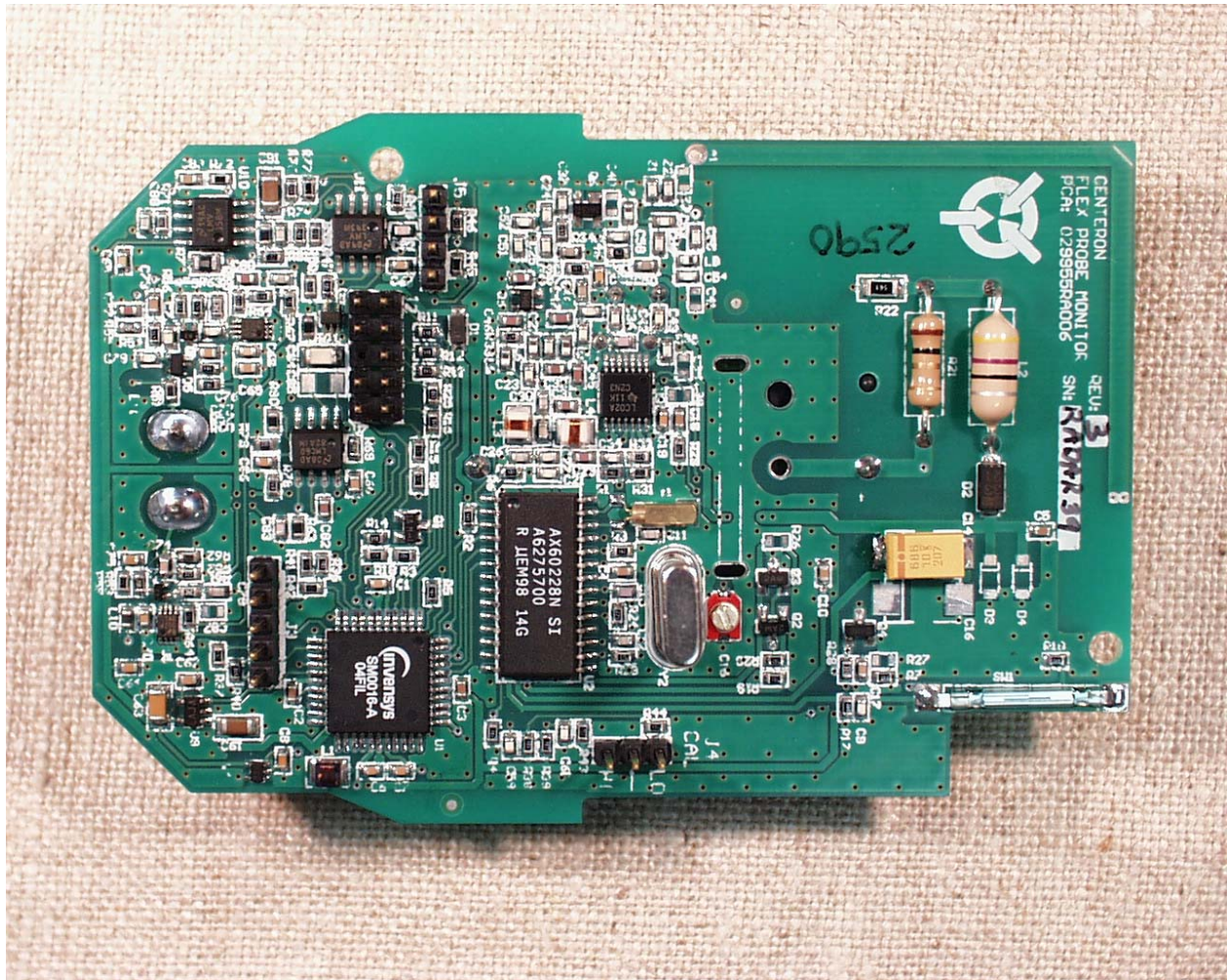


Figure 4: Photograph of component side of device under test

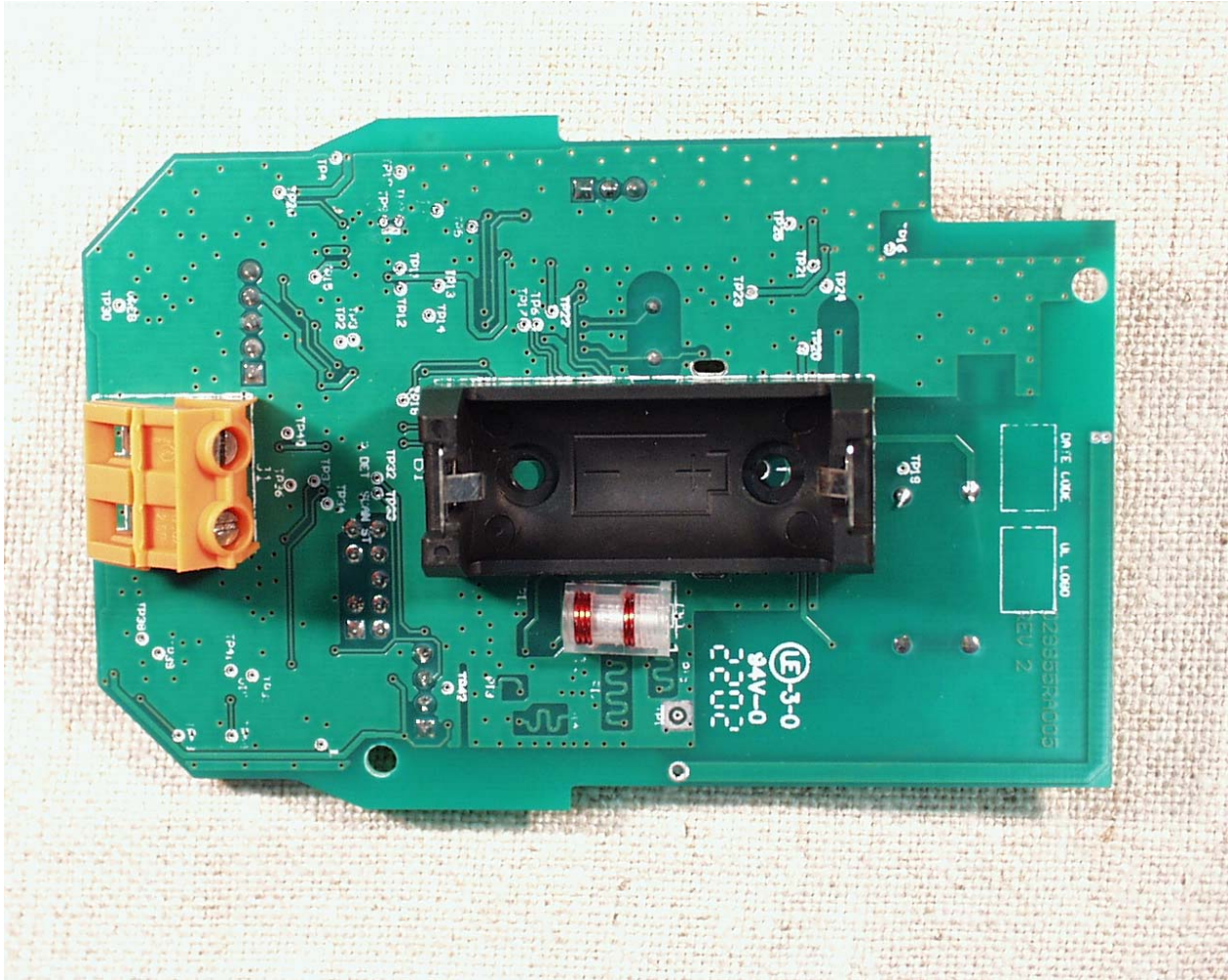


Figure 5: Photograph of solder side of device under test